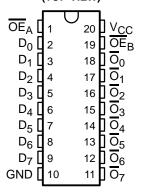
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- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT540T
 - 48-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT540T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

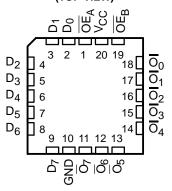
description

The 'FCT540T inverting buffers/line drivers can be employed as memory address drivers, clock drivers, and bus-oriented transmitters/receivers. These devices provide speed and drive capabilities equivalent to their fastest bipolar-logic counterparts, while reducing power dissipation. The input and output voltage levels allow direct interface with TTL, NMOS, and CMOS devices without external components.

CY54FCT540T...D PACKAGE CY74FCT540T...Q PACKAGE (TOP VIEW)



CY54FCT540T . . . L PACKAGE (TOP VIEW)



These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

ORDERING INFORMATION

TA	PACI	KAGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	4.1	CY74FCT540CTQCT	FCT540C
–55°C to 125°C	CDIP – D	Tube	4.7	CY54FCT540CTDMB	
-55-0 10 125-0	LCC – L	Tube	4.7	CY54FCT540CTLMB	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

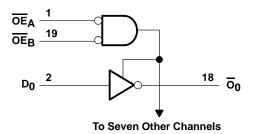


FUNCTION TABLE

	INPUTS		OUTPUT
OEA	OE _B	D	ō
L	L	L	Н
L	L	Н	L
Н	Н	Χ	z

H = High logic level, L = Low logic level, X = Don't care, Z = High-impedance state

logic diagram (positive logic)



absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ _{JA} (see Note 1): Q package	68°C/W
Ambient temperature range with power applied, T _A	–65°C to 135°C
Storage temperature range, T _{stg}	−65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 2)

		CY!	54FCT54	0T	CY7	74FCT54	.0Т	UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	ONIT
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
VIH	High-level input voltage	2			2			V
VIL	Low-level input voltage			0.8			0.8	V
ІОН	High-level output current			-12			-32	mA
loL	Low-level output current			48			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 2: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETED	TEST COMPLETIONS		CY	54FCT54	IOT	CY	74FCT54	10T	UNIT
PARAMETER	TEST CONDITIONS		MIN	TYP [†]	MAX	MIN	TYP [†]	MAX	UNII
V., ,	$V_{CC} = 4.5, V$ $I_{IN} = -18 \text{ mA}$			-0.7	-1.2				V
VIK	$V_{CC} = 4.75 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$						-0.7	-1.2	V
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$		2.4	3.3					
Voн	V _{CC} = 4.75 V I _{OH} = -32 mA					2			V
	$I_{OH} = -15 \text{ mA}$					2.4	3.3		
Vo	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 48 \text{ mA}$			0.3	0.55				V
VOL	$V_{CC} = 4.75 \text{ V}, \qquad I_{OL} = 64 \text{ mA}$						0.3	0.55	V
V_{hys}	All inputs			0.2			0.2		V
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$				5				^
1	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = V_{CC}$							5	μΑ
I.e.	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$				±1				
lΉ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$							±1	μΑ
1	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$				±1				^
۱۱۲	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$							±1	μΑ
1	V _{CC} = 5.5 V, V _{OUT} = 2.7 V				10				A
IOZH	V _{CC} = 5.25 V, V _{OUT} = 2.7 V							10	μΑ
1	V _{CC} = 5.5 V, V _{OUT} = 0.5 V				-10				
IOZL	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0.5 \text{ V}$							-10	μΑ
. +	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$		-60	-120	-225				A
los‡	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$					-60	-120	-225	mA
l _{off}	$V_{CC} = 0 \text{ V}, \qquad V_{OUT} = 4.5 \text{ V}$				±1			±1	μΑ
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC}$	– 0.2 V		0.1	0.2				mA
ICC	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC}$	– 0.2 V					0.1	0.2	IIIA
	V _{CC} = 5.5 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open			0.5	2				
ΔICC	V _{CC} = 5.25 V, V _{IN} = 3.4 V§, f ₁ = 0, Outputs open						0.5	2	mA
1 ¶	V_{CC} = 5.5 V, 50% duty cycle, Outputs open, One bit switching at f ₁ = 10 MHz, \overline{OE}_A = \overline{OE}_B = GND or \overline{OE}_A = GND and \overline{OE}_B = V_{CC} $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V	.,		0.06	0.12				mA/
^I CCD [¶]	V_{CC} = 5.25 V, 50% duty cycle, Outputs open, One bit switching at f ₁ = 10 MHz, \overline{OE}_A = \overline{OE}_B = GND or \overline{OE}_A = GND and \overline{OE}_B = V_{CC} $V_{IN} \le 0.2$ V or $V_{IN} \ge V_{CC} - 0.2$ V	;,					0.06	0.12	MHz

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ios tests should be performed last.

[§] Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

This parameter is derived for use in total power-supply calculations.

CY54FCT540T, CY74FCT540T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

DADAMETED		TEST CONDITIONS		CY	54FCT54	IOT	CY	74FCT54	0T	LINUT
PARAMETER		TEST CONDITIONS				MAX	MIN	TYP [†]	MAX	UNIT
	V _{CC} = 5.5 V, Outputs open,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	$\overline{OE}_A = \overline{OE}_B =$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1	2.4				
	$\frac{\text{GND}}{\text{OE}_{A}}$ = GND and $\frac{\text{OE}_{B}}{\text{OE}_{B}}$ = V _{CC}	GND or OEA = GND and at f1 = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		1.3	2.6				
I _C #			$V_{IN} = 3.4 \text{ V or GND}$		3.3	10.6				mA
IC"	V _{CC} = 5.25 V, Outputs open,	One bit switching at f ₁ = 10 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	ША
	$\overline{OE}_A = \overline{OE}_B =$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1	2.4	
	$\frac{\text{GND}}{\text{OE}}$ = GND and	Eight bits switching at f ₁ = 2.5 MHz	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					1.3	2.6	
	$\overline{OE}_B = V_{CC}$	at 50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					3.3	10.6	
C _i								5	10	pF
Co		_						9	12	pF

[†] Typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

Where:

IC = Total supply current

I_{CC} = Power-supply current with CMOS input levels

 ΔI_{CC} = Power-supply current for a TTL high input ($V_{IN} = 3.4 \text{ V}$)

 D_H = Duty cycle for TTL inputs high N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

= Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

Values for these conditions are examples of the ICC formula.



 $^{^{\#}}$ IC = ICC + Δ ICC \times DH \times NT + ICCD (f₀/2 + f₁ \times N₁)

CY54FCT540T, CY74FCT540T 8-BIT BUFFERS/LINE DRIVERS WITH 3-STATE OUTPUTS SCCS029A - MAY 1994 - REVISED OCTOBER 2001

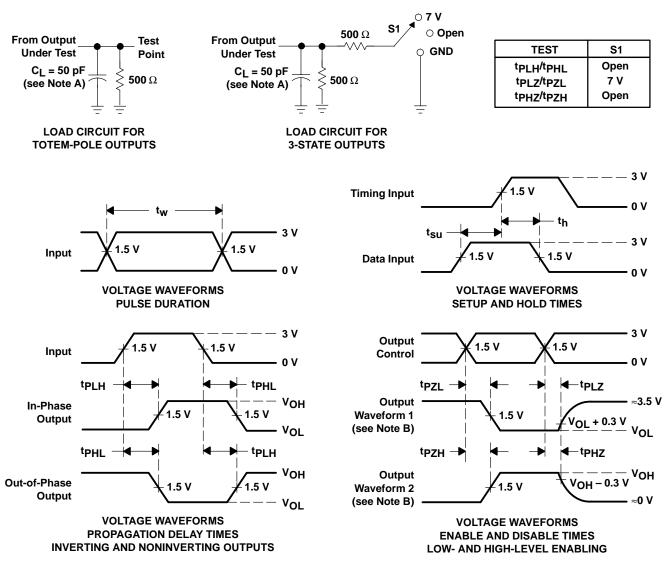
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY54FCT	540CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	UNIT
^t PLH	D	ō	1.5	4.7	ns
t _{PHL}	D	0	1.5	4.7	115
^t PZH	ŌĒ	ō	1.5	6.5	ne
tPZL	OL)	1.5	6.5	ns
^t PHZ	ŌĒ	ō	1.5	5.7	ne
t _{PLZ}	J SE	9	1.5	5.7	ns

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY74FCT	540CT	UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	UNIT
^t PLH	D	ō	1.5	4.1	20
^t PHL	В	O	1.5	4.1	ns
^t PZH	ŌĒ	ō	1.5	5.8	ns
t _{PZL}	OE .	O	1.5	5.8	115
^t PHZ	ŌĒ	ō	1.5	5.2	
t _{PLZ}	UE UE	0	1.5	5.2	ns

PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms



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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
5962-9222006MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9222006MR A	Samples
5962-9223701M2A	ACTIVE	LCCC	FK	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223701M2A CY54FCT 541TLMB	Samples
5962-9223701MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223701MR A CY54FCT541TDMB	Samples
5962-9223705MRA	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223705MR A	Samples
CY54FCT541TDMB	ACTIVE	CDIP	J	20	1	Non-RoHS & Green	SNPB	N / A for Pkg Type	-55 to 125	5962-9223701MR A CY54FCT541TDMB	Samples
CY54FCT541TLMB	ACTIVE	LCCC	FK	20	1	Non-RoHS & Non-Green	SNPB	N / A for Pkg Type	-55 to 125	5962- 9223701M2A CY54FCT 541TLMB	Samples
CY74FCT540CTQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT540C	Samples
CY74FCT541ATPC	ACTIVE	PDIP	N	20	20	RoHS & Non-Green	NIPDAU	N / A for Pkg Type	-40 to 85	CY74FCT541ATPC	Samples
CY74FCT541ATQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541A	Samples
CY74FCT541ATSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541A	Samples
CY74FCT541ATSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541A	Samples
CY74FCT541CTQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541C	Samples
CY74FCT541CTSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541C	Samples
CY74FCT541CTSOCT	ACTIVE	SOIC	DW	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541C	Samples
CY74FCT541TQCT	ACTIVE	SSOP	DBQ	20	2500	RoHS & Green	NIPDAU	Level-2-260C-1 YEAR	-40 to 85	FCT541	Samples

PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead finish/ Ball material	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
CY74FCT541TSOC	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	FCT541	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (CI) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead finish/Ball material Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

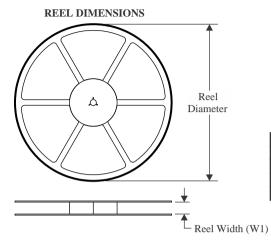
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PACKAGE MATERIALS INFORMATION

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TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

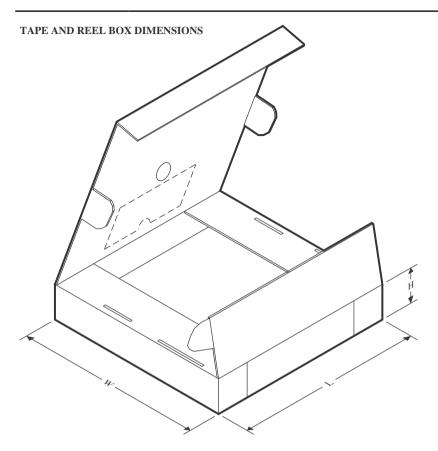


*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT540CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541ATQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT541CTQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT541CTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1
CY74FCT541TQCT	SSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1



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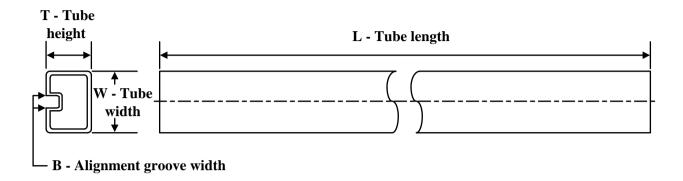
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins SPQ L		Length (mm)	Width (mm)	Height (mm)
CY74FCT540CTQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT541ATQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT541ATSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT541CTQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0
CY74FCT541CTSOCT	SOIC	DW	20	2000	367.0	367.0	45.0
CY74FCT541TQCT	SSOP	DBQ	20	2500	356.0	356.0	35.0

PACKAGE MATERIALS INFORMATION

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TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
5962-9223701M2A	FK	LCCC	20	1	506.98	12.06	2030	NA
CY54FCT541TLMB	FK	LCCC	20	1	506.98	12.06	2030	NA
CY74FCT541ATPC	N	PDIP	20	20	506	13.97	11230	4.32
CY74FCT541ATSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT541CTSOC	DW	SOIC	20	25	507	12.83	5080	6.6
CY74FCT541TSOC	DW	SOIC	20	25	507	12.83	5080	6.6

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